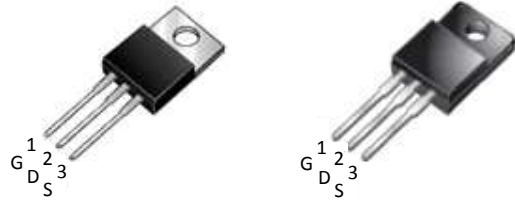


| | |
|---|---|
| 650V / 12A N-Channel Enhancement Mode MOSFET | $650V, R_{DS(ON)}=0.8\Omega@V_{GS}=10V, I_D=6.0A$ |
|---|---|

Features

- Low ON Resistance
- Fast Switching
- Low Gate Charge & Low C_{RSS}
- Fully Characterized Avalanche Voltage and Current
- Specially Designed for AC Adapter, Battery Charger and SMPS
- In compliance with EU RoHs 2002/95/EC Directives



TO-220AB

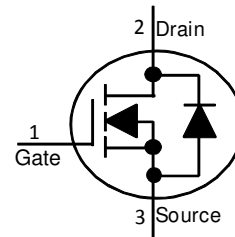
ITO-220AB

Mechanical Information

- Case: TO-220AB / ITO-220AB Molded Plastic
- Terminals : Solderable per MIL-STD-750, Method 2026

Marking & Ordering Information

| TYPE | MARKING | PACKAGE | PACKING |
|-----------|---------|-----------|------------|
| HY12N65T | 12N65T | TO-220AB | 50PCS/TUBE |
| HY12N65FT | 12N65FT | ITO-220AB | 50PCS/TUBE |



Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

| Parameter | | Symbol | HY12N65T | HY12N65FT | Units |
|--|------------------|----------------|-------------|-----------|------------|
| Drain-Source Voltage | | V_{DS} | 650 | | V |
| Gate-Source Voltage | | V_{GS} | ± 30 | | V |
| Continuous Drain Current | $T_c=25^\circ C$ | I_D | 12 | 12 | A |
| Pulsed Drain Current ¹⁾ | | I_{DM} | 48 | 48 | A |
| Maximum Power Dissipation | $T_c=25^\circ C$ | P_D | 175 | 52 | W |
| Derating Factor | | | 1.4 | 0.42 | |
| Avalanche Energy with Single Pulse $I_{AS}=12A, V_{DD}=90V, L=10.5mH$ | | E_{AS} | 760 | | mJ |
| Operating Junction and Storage Temperature Range | | T_J, T_{STG} | -55 to +150 | | $^\circ C$ |

Note : 1. Maximum DC current limited by the package

Thermal Characteristics

| PARAMETER | Symbol | HY12N65T | HY12N65FT | Units |
|--|-----------------|----------|-----------|--------------|
| Junction-to-Case Thermal Resistance | $R_{\theta JC}$ | 0.7 | 2.4 | $^\circ C/W$ |
| Junction-to Ambient Thermal Resistance | $R_{\theta JA}$ | 62.5 | 100 | $^\circ C/W$ |

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Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Test Condition | Min. | Typ. | Max. | Units |
|----------------------------------|--------------|--|------|------|-----------|----------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 650 | - | - | V |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2.0 | - | 4.0 | V |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS}=10V, I_D=6.0A$ | - | 0.69 | 0.8 | Ω |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=650V, V_{GS}=0V$ | - | - | 10 | μA |
| Gate Body Leakage | I_{GSS} | $V_{GS}=\pm 30V, V_{DS}=0V$ | - | - | ± 100 | nA |
| Dynamic | | | | | | |
| Total Gate Charge | Q_g | $V_{DS}=520V, I_D=12A,$ $V_{GS}=10V$ | - | 42.6 | 52 | nC |
| Gate-Source Charge | Q_{gs} | | - | 8.2 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 12.8 | - | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD}=325V, I_D=12A$ $V_{GS}=10V, R_G=25\Omega$ | - | 14.6 | 20 | ns |
| Turn-On Rise Time | t_r | | - | 22.6 | 32 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 65.2 | 85 | |
| Turn-Off Fall Time | t_f | | - | 22.8 | 36 | |
| Input Capacitance | C_{iss} | $V_{DS}=25V, V_{GS}=0V$ $f=1.0\text{MHz}$ | - | 1400 | 2050 | pF |
| Output Capacitance | C_{oss} | | - | 175 | 210 | |
| Reverse Transfer Capacitance | C_{rss} | | - | 5.5 | 12 | |
| Source-Drain Diode | | | | | | |
| Max. Diode Forward Current | I_S | - | - | - | 12 | A |
| Max.Pulsed Source Current | I_{SM} | - | - | - | 48 | A |
| Diode Forward Voltage | V_{SD} | $I_S=12A, V_{GS}=0V$ | - | - | 1.4 | V |
| Reverse Recovery Time | t_{rr} | $V_{GS}=0V, I_F=12A$ $di/dt=100A/\mu s$ | - | 460 | - | ns |
| Reverse Recovery Charge | Q_{rr} | | - | 4.6 | - | μC |

NOTE : Plus Test : Pluse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

Typical Characteristics Curves ($T_C=25^\circ\text{C}$, unless otherwise noted)

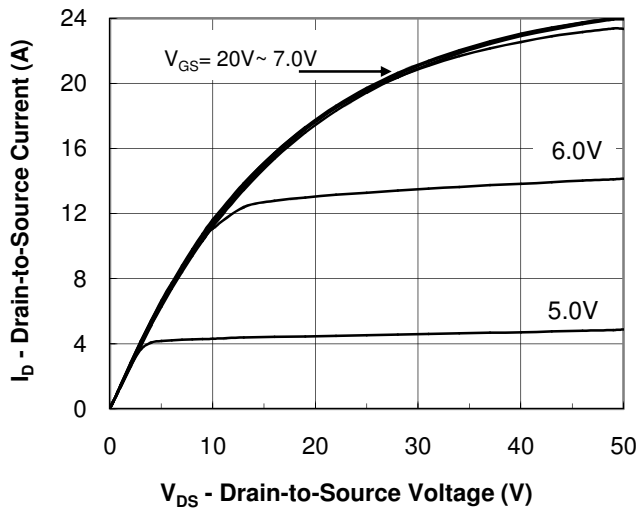


Fig.1 Output Characteristic

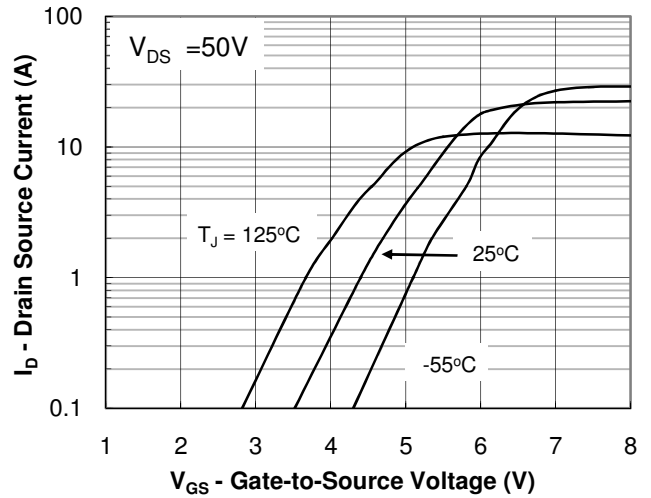


Fig.2 Transfer Characteristic

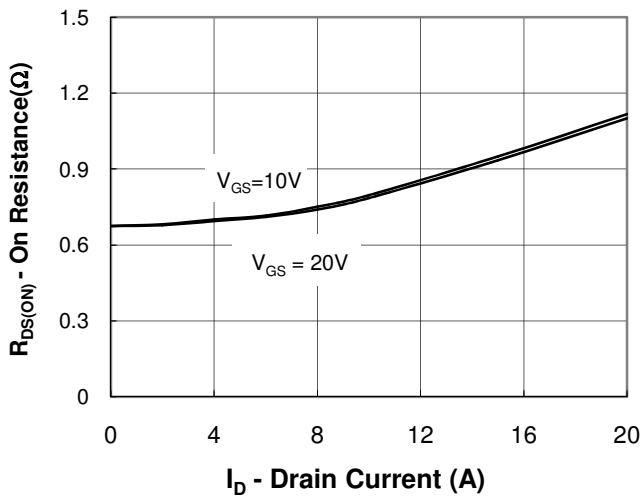


Fig.3 On-Resistance vs Drain Current

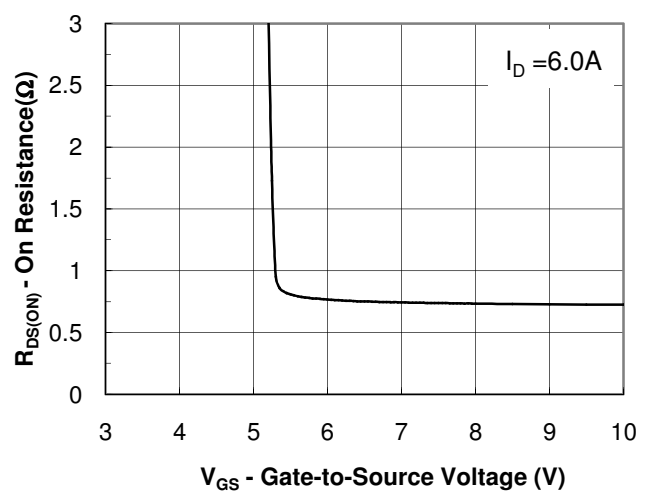


Fig.4 On-Resistance vs Gate to Source Voltage

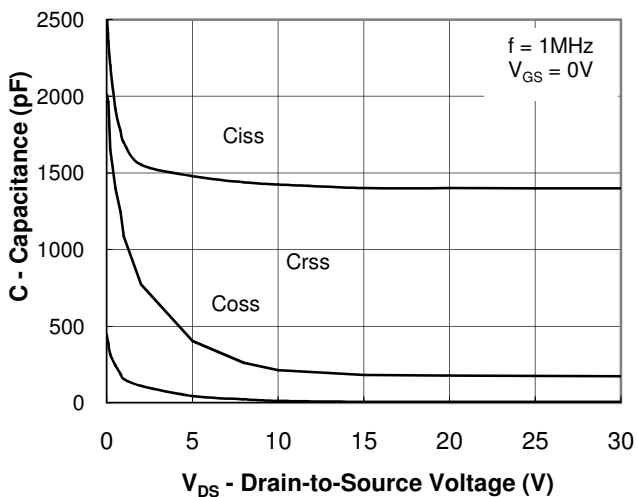


Fig.5 Capacitance Characteristic

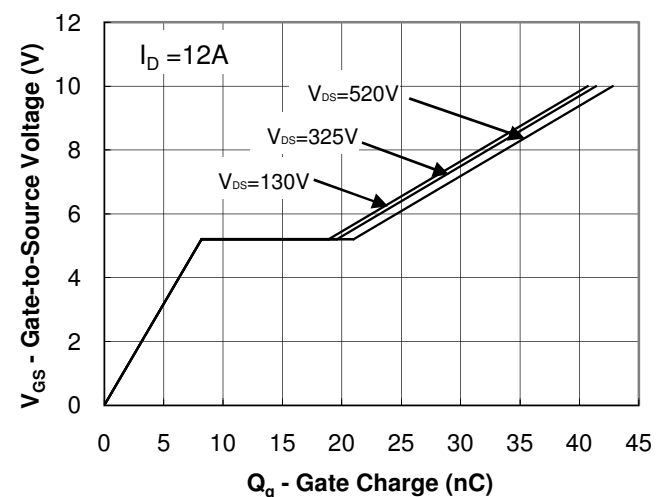


Fig.6 Gate Charge Characteristic

Typical Characteristics Curves ($T_C=25^\circ\text{C}$, unless otherwise noted)

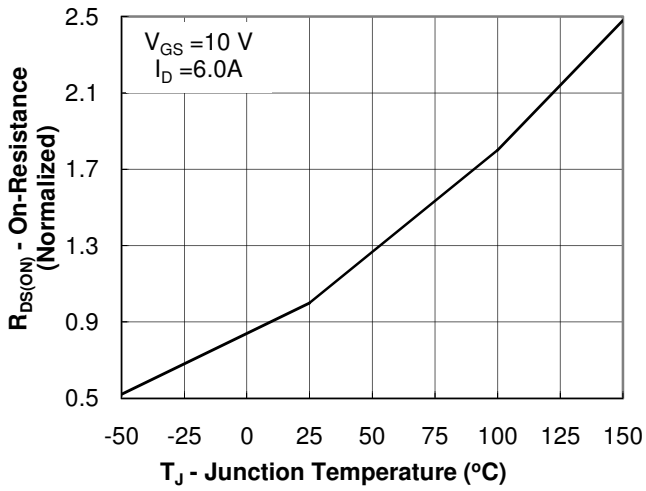


Fig.7 On-Resistance vs Junction Temperature

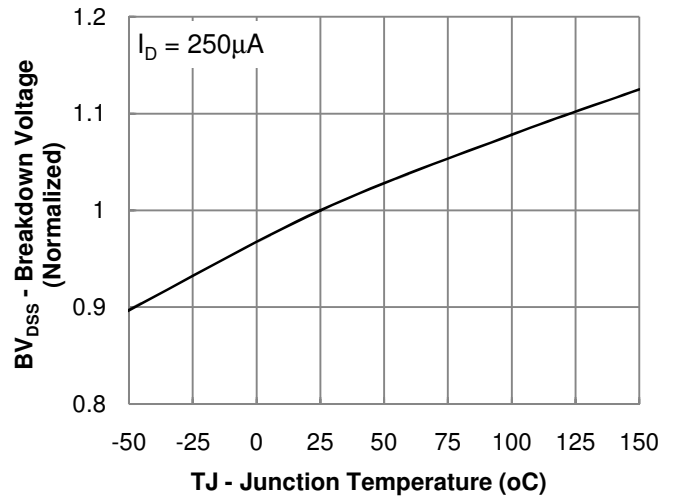


Fig.8 Breakdown Voltage vs Junction Temperature

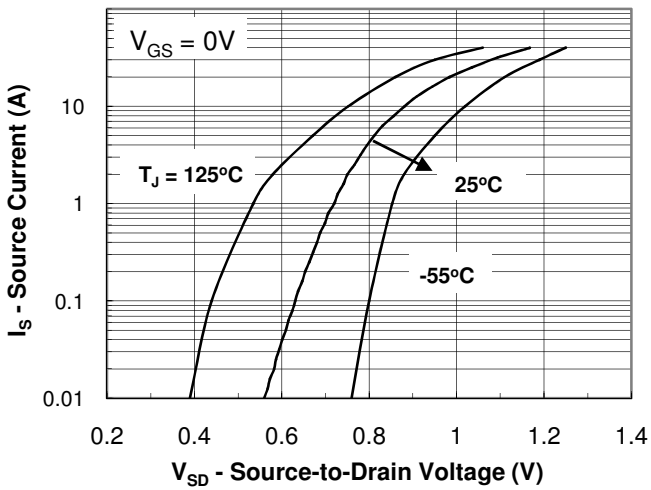


Fig.9 Body Diode Forward Voltage Characteristic